

L Number	Hits	Search Text	DB	Time stamp
-	2	("20020170064").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 11:34
-	1002	375/240.25	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 11:34
-	0	375/240.25 and watermark and interlaced and matrix	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 11:35
-	74	375/240.25 and interlaced and matrix	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 11:35
-	60	(375/240.25 and interlaced and matrix) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 13:54
-	2	("5991426").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 11:41
-	60	(375/240.25 and interlaced and matrix) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 13:54
-	32	((375/240.25 and interlaced and matrix) and @ay<2001) and (matrix same (DCT or idct))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:21
-	1666153	(chamber or (spin adj (unit or chamber)) or (processing adj (unit or chamber)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:31
-	68039	((chamber or (spin adj (unit or chamber)) or (processing adj (unit or chamber)))) and (wafer or waffer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:23
-	9	((((chamber or (spin adj (unit or chamber)) or (processing adj (unit or chamber)))) and (wafer or waffer)) and ((camera or ccd or imager) same (developer or (development adj (chamger or unit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:27
-	68736	silicon adj wafer\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:27

-	19068	(silicon adj wafer\$2) and ((chamber or (spin adj (unit or chamber))) or (processing adj (unit or chamber))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:28
-	2157	((silicon adj wafer\$2) and ((chamber or (spin adj (unit or chamber))) or (processing adj (unit or chamber)))) and (camera or ccd or imager)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:28
-	0	((silicon adj wafer\$2) and ((chamber or (spin adj (unit or chamber))) or (processing adj (unit or chamber)))) and (camera or ccd or imager) and (manufactor\$5 same wafer\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:29
-	1467	((silicon adj wafer\$2) and ((chamber or (spin adj (unit or chamber))) or (processing adj (unit or chamber)))) and (camera or ccd or imager) and (monitor or display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:30
-	442	((silicon adj wafer\$2) and ((chamber or (spin adj (unit or chamber))) or (processing adj (unit or chamber)))) and (camera or ccd or imager) and (monitor or display) and @ay<2000	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 14:30
-	112	((silicon adj wafer\$2) and ((chamber or (spin adj (unit or chamber))) or (processing adj (unit or chamber)))) and (camera or ccd or imager) and (monitor or display) and @ay<2000 and ((chamber or (spin adj (unit or chamber))) or (processing adj (unit or chamber))) same (camera or ccd or imager))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 16:34
-	11210	((chamber or (spin adj (unit or chamber))) or (develop\$6 adj (unit or chamber))) same (camera or ccd or imager))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 17:17
-	778	((chamber or (spin adj (unit or chamber))) or (develop\$6 adj (unit or chamber))) same (camera or ccd or imager)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 16:35
-	336	((chamber or (spin adj (unit or chamber))) or (develop\$6 adj (unit or chamber))) same (camera or ccd or imager)) and wafer and @ay<2000	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 16:39
-	285	(chamber or (spin adj (unit or chamber))) or (develop\$6 adj (unit or chamber)) and ((develop\$6 adj (unit or chamber)) same (camera or ccd or imager))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 17:36
-	0	((chamber or (spin adj (unit or chamber))) or (develop\$6 adj (unit or chamber))) and ((develop\$6 adj (unit or chamber)) same (camera or ccd or imager)) and @ay<2000 and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 17:42
-	208	((chamber or (spin adj (unit or chamber))) or (develop\$6 adj (unit or chamber))) and ((develop\$6 adj (unit or chamber)) same (camera or ccd or imager)) and @ay<2000	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 17:43
-	2	5742395.URPN.	USPAT	2004/07/26 18:37
-	2	("4740708" "4929081").PN.	USPAT	2004/07/26 18:37

-	7	("3876303" "4650983" "4677301" "4774158" "4806457" "4900939" "4908656").PN.	USPAT	2004/07/26 18:58
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L Number	Hits	Search Text	DB	Time stamp
-	59527	silicon adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:12
-	15347	(silicon adj wafer) and (photolithography or lithograph\$7)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:13
-	7657	((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:13
-	2315	((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:16
-	266	(((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit))) and camera	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:14
-	117	((((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit))) and camera) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:15
-	2316	((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:40
-	40	(((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)) same camera)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:16
-	13	(((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)) same camera)) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:16
-	6447	((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:41
-	136	(((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9)) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:41

-	96	(((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9)) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd))) not (((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)) same camera))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 14:26
-	39	(((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9)) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd))) not (((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)) same camera))) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 14:25
-	151	(silicon adj wafer) and (photolithography or lithograph\$7) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd)) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 14:33
-	39	(((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9)) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd))) not (((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)) same camera))) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 14:26
-	96	(((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9)) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd))) not (((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)) same camera))) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 14:26
-	112	((silicon adj wafer) and (photolithography or lithograph\$7) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd)) and @ay<2001) not (((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9)) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd))) not (((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)) same camera)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 14:26
-	56	(silicon adj wafer) and (photolithography or lithograph\$7) and developer and (camera or ccd) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 15:00

-	39	((silicon adj wafer) and (photolithography or lithograph\$7) and developer and (camera or ccd) and @ay<2001) not (((silicon adj wafer) and (photolithography or lithograph\$7) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd)) and @ay<2001) or ((((((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and ((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9)) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit) or develop\$9) same (camera or ccd))) not (((silicon adj wafer) and (photolithography or lithograph\$7)) and photoresist) and (((spray adj unit) or (spin adj unit) or chamber or (processing adj unit)) same camera))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 14:33
-	0	(silicon adj wafer) and (photolithography or lithograph\$7) and (develop near2 (chamber or unit)) and (camera or ccd) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 15:03
-	18	(silicon adj wafer) and (photolithography or lithograph\$7) and (develop\$5 near2 (chamber or unit)) and (camera or ccd) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 15:03

L Number	Hits	Search Text	DB	Time stamp
-	2	"6686130"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 15:05
-	10	("4647172" "4851311" "4998021" "5427878" "5898478" "5977558" "6187488" "6191397" "6238936" "6251544").PN.	USPAT	2004/08/04 15:05
-	2	((("4647172" "4851311" "4998021" "5427878" "5898478" "5977558" "6187488" "6191397" "6238936" "6251544").PN.) and (camera or ccd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 15:51
-	15544	430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:11
-	24	4647172.URPN.	USPAT	2004/08/04 15:53
-	47	4851311.URPN.	USPAT	2004/08/04 16:05
-	9631	(430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:11
-	1192	((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:12
-	446	((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and photoresist\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:14
-	369	(((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and photoresist\$2) and (wafer\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:14
-	670	(((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:14
-	556	(((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)) and (wafer\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:15
-	344	(((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)) and (wafer\$2)) and @ay<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:49
-	7	(((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)) and (wafer\$2)) and @ay<2001) and (develop\$6.ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:44

-	4	("5393624" "6161969" "6197372" "6198981").PN.	USPAT	2004/08/04 16:32
-	2	((((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)) and (wafer\$2)) and @ay<2001) and ((develop\$6.ti.) near2 (unit or system or chamber)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:45
-	47	((((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)) and (wafer\$2)) and @ay<2001) and (develop\$6 same (imager\$2 or camera\$2 or ccd\$2)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:49
-	43	((((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)) and (wafer\$2)) and @ay<2001) and (develop\$6 same (imager\$2 or camera\$2 or ccd\$2))) not (((((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)) and (wafer\$2)) and @ay<2001) and (develop\$6.ti.)) or ("5393624" "6161969" "6197372" "6198981").PN.) or (((((((430/30 or 250/573 or 356/436 or 356/442 or 396/570 or 430/311 or 430/325 or 438/16 or 396/569 or 396/570 or 430/30 or 438/948) and (develop\$6)) and (imager\$2 or camera\$2 or ccd\$2)) and (photoresist\$2 or resist)) and (wafer\$2)) and @ay<2001) and ((develop\$6.ti.) near2 (unit or system or chamber))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:50